Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Withdrawn-Currently Amended) A method of forming a patterned film by frame plating, the patterned film being made of a conductive material and including a plurality of linear portions disposed side by side, a linear portion by frame plating, the method comprising:

forming a frame having an undercut near a bottom thereof on a base layer; and forming the patterned film by plating through the use of the frame such that <u>each of</u> the linear <u>portions portion</u> has a first portion and a second portion, wherein the second portion is closer to the base layer than the first portion, and wherein the second portion touches the base layer and has a width greater than a width of the first portion <u>taken at an interface between the first portion and the second portion</u>, and wherein adjacent ones of the first portions have a space therebetween, adjacent ones of the second portions is greater than the space between the adjacent ones of the second portions.

- 2. (Canceled).
- 3. (Currently Amended) A patterned film made of a conductive material, the patterned film being disposed on a base layer and including a <u>plurality of linear portions</u> disposed side by side, portion, wherein <u>each of</u> the linear <u>portions portion</u> has a first portion and a second portion, wherein the second portion is closer to the base layer than the first portion, and wherein the second portion touches the base layer, the second portion having a width greater than a width of the first portion taken at an interface between the first portion and the second portion, and wherein adjacent ones of the first portions have a space therebetween, adjacent ones of the second portions have a space therebetween, and the space

between the adjacent ones of the first portions is greater than the space between the adjacent ones of the second portions.

4. (Canceled).